# P6KE50CA

# **Transient Voltage Suppressors**

Pppm: 600W

#### FEATURE

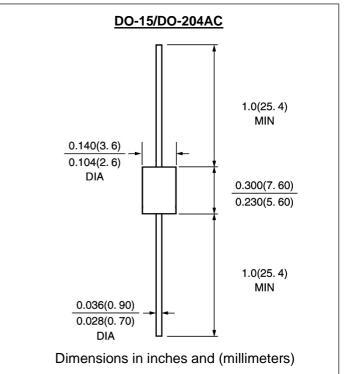
Low power loss High surge capability Glass passivated chip junction High temperature soldering guaranteed  $250^{\circ}C/10sec/0.375''$  lead length at 5 lbs tension

### **MECHANICAL DATA**

Terminal: Plated axial leads solderable per MIL-STD 202E, method 208C

Case: Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy Polarity: no marking

Mounting position: any



MAXIMUM (TA = 25 ℃ unless)		ed)	
PARAMETER	SYMBOL	P6KE50CA	units
Peak power dissipation with a 10/1000 µs waveform (1) (Fig. 1)	P <sub>PPM</sub>	600	W
Peak pulse current with a 10/1000 µs waveform (1)	I <sub>PPM</sub>	8.3	A
Breakdown Voltage at I <sub>T</sub> =1mA	V <sub>BR</sub>	47.6min 52.5max	V
Maximum Reverse Leakage at $V_{WM}$ =42.7V	I <sub>R</sub>	1.0	μ Α
Maximum Clamping Voltage at IPPM	V <sub>c</sub>	72	V
Power dissipation on infinite heatsink at $T_L = 75 \ C$ (Fig. 5)	P <sub>D</sub>	5.0	W
Typical thermal resistance junction-to-lead	Rth(jl)	20	℃/W
Typical thermal resistance junction-toambient	Rth(ja)	75	°C/W
Storage and Operating Junction Temperature	Tstg,Tj	-55 to +175	°C

Note:

(1) Non-repetitive current pulse, per Fig. 3 and derated above TA = 25  $^{\circ}{\rm C}$  per Fig. 2

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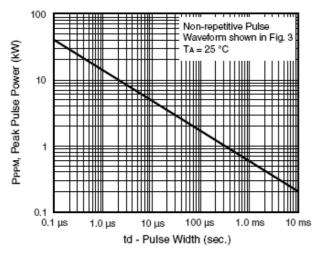


Figure 1. Peak Pulse Power Rating Curve

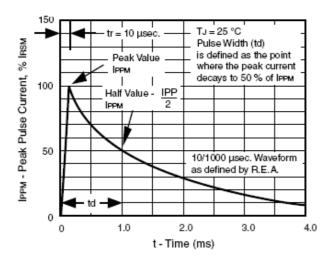


Figure 3. Pulse Waveform

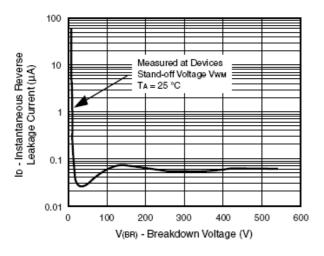


Figure 5. Typical Reverse Leakage Characteristics

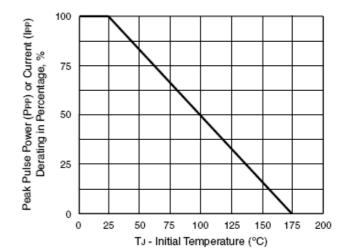
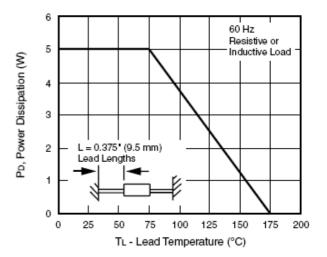


Figure 2. Pulse Power or Current versus Initial Junction Temperature





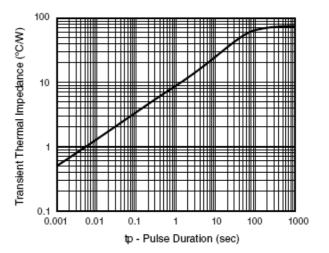


Figure 6. Typical Transient Thermal Impedance

#### RATINGS AND CHARACTERISTIC CURVES P6KE50CA